

Class	Subclass
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U.S. UTILITY Patent Application

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APPLICATION NO. 09/848997	CONT/PRIOR	CLASS 438	SUBCLASS 690	ART UNIT 2812 <i>J. J. S.</i>	EXAMINER <i>Guerrero</i>
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APPLICANT  
Lup, Leong

TITLE  
Thermal mechanical planarization in integrated circuits

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PTO-2040  
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